Product / Process Change Notification



N° 2019-159-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Early PCN: Change of the assembly location from AMKOR, Korea to ASE, Taiwan and update of the data sheet affecting dedicated products in package BGA 292

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 10. June 2020.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

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▶ **Products affected:** Please refer to attached affected product list 1_cip19159_a

Detailed Change Information:

Subject: Change of the assembly location from AMKOR, Korea to ASE, Taiwan

and update of the data sheet affecting dedicated products in package

BGA 292.

Reason: Harmonization of the production site strategy affecting Infineon's

AURIX™ product family

Description:	Old	<u>New</u>	
Assembly location:	■ Amkor (plant ATK4), Korea	■ ASE (plant K5), Taiwan	
Die attach material:	■ Glue ,ABLEBOND 2300'	■ Glue ,ABLEBOND 2100A'	
Data sheet update:	Rev. 1.0 (TC27xC) Rev. 1.1 (TC29xB) Rev. 1.0 (TC29xBC)	Rev. 1.1 (TC27xC) Rev. 1.2 (TC29xB) Rev. 1.1 (TC29xBC)	
Sales part number:	■ Please refer to 1_cip19159_a attached.		
Substrate/ Core material:	■ MGC HL832NS	■ DS 7409HGB	
Substrate/Core material supplier:	■ KCC	■ UMTC	

The traceability is ensured by

- lot number
- Infineon sales part number

Impact of Change:

No change in form, fit or function.

For Automotive products only: DeQuMa-ID: SEM-DS-02; SEM-PA-07; SEM-PA-18; SEM-PA-09; SEM-PA-16

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► Attachments: Affected product list 1_cip19159_a

▶ Time Schedule:

Final qualification plan: Available on demand

Final qualification report: Mid of August 2020

First samples available: June 2020

Intended start of delivery: December 2020 (or earlier upon customer approval)

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N°2019-159-A

Change of the assembly location from AMKOR, Korea to ASE, Taiwan and update of the data sheet affecting dedicated products in package BGA 292



Sales Name	SP number	SP number_new	OPN	Package
SAK-TC277T-64F200S CA	SP001146094	SP005337784	TC277T64F200SCAKXUMA1	PG-LFBGA-292
SAK-TC277TC-64F200S CA	SP001217636	SP005337788	TC277TC64F200SCAKXUMA1	PG-LFBGA-292
SAK-TC277TP-64F200S CA	SP001146098	SP005337786	TC277TP64F200SCAKXUMA1	PG-LFBGA-292
SAK-TC297T-128F300S BB	SP001265596	SP005411077	TC297T128F300SBBKXUMA1	PG-LFBGA-292
SAK-TC297T-96F300N BC	SP001684616	SP005411081	TC297T96F300NBCKXUMA1	PG-LFBGA-292
SAK-TC297T-96F300S BB	SP001265616	SP005411078	TC297T96F300SBBKXUMA1	PG-LFBGA-292
SAK-TC297TC-96F300S BB	SP001265598	SP005411079	TC297TC96F300SBBKXUMA1	PG-LFBGA-292
SAK-TC297TC-96F300S BC	SP001611504	SP005411082	TC297TC96F300SBCKXUMA1	PG-LFBGA-292
SAK-TC297TP-128F300N BC	SP001396392	SP005411083	TC297TP128F300NBCKXUMA1	PG-LFBGA-292
SAK-TC297TP-128F300S BB	SP001207656	SP005411080	TC297TP128F300SBBKXUMA1	PG-LFBGA-292
SAK-TC297TP-128F300S BC	SP001366094	SP005411084	TC297TP128F300SBCKXUMA1	PG-LFBGA-292
SAK-TC297TP-96F300N BC	SP001662190	SP005425539	TC297TP96F300NBCKXUMA1	PG-LFBGA-292
SAK-TC297TP-96F300S BB	SP001001102	SP005425540	TC297TP96F300SBBKXUMA1	PG-LFBGA-292
SAL-TC277T-64F200S CA	SP001256016	SP005339852	TC277T64F200SCALXUMA1	PG-LFBGA-292